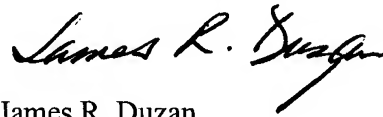


**REMARKS**

No new matter has been added. The amendments to the claims address typographical and spelling errors, and improve antecedent basis. The amendments do not affect, or surrender, any scope of any claim as originally filed.

The Applicants again request entry of the amendments as set forth herein and in the Appendices attached hereto prior to examination of the application on the merits.

Respectfully submitted,



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JRD/csw

Enclosures: Appendices A and B  
Replacement Sheet  
Annotated Sheet Showing Changes

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IN THE CLAIMS:

Claims 1 through 9 have been amended herein. All of the pending claims 1 through 24 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

Listing of Claims:

1. (Currently amended) A ~~laser-markable~~ laser-markable tape for marking a semiconductor device comprising:  
a tape comprising a flexible film material; and  
a ~~multi-layer~~ multilayer adhesive including:  
a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components, said electromagnetic radiation-curable components providing a ~~laser-markable~~ laser-markable surface upon exposure to an electromagnetic radiation source; and  
a second adhesive layer disposed between said tape and said first outermost adhesive layer.
2. (Currently amended) The ~~laser-markable~~ laser-markable tape of claim 1, wherein said ~~laser-markable~~ laser-markable tape is adhered to at least a portion of a surface of a bare semiconductor die.
3. (Currently amended) The ~~laser-markable~~ laser-markable tape of claim 2, wherein said ~~laser-markable~~ laser-markable tape is adhered to a bare semiconductor die surface subjected to a backgrinding process.

4. (Currently amended) The ~~laser-markable~~ laser-markable tape of claim 2, wherein said first outermost adhesive layer is cured upon exposure to said electromagnetic radiation source to thereby attach said first outermost adhesive layer to said at least a portion of said surface of said bare semiconductor die.

5. (Currently amended) The ~~laser-markable~~ laser-markable tape of claim 4, wherein said curing of said first outermost adhesive layer results in a loss of adhesion between said first outermost adhesive layer and said second adhesive layer.

6. (Currently amended) The ~~laser-markable~~ laser-markable tape of claim 4, wherein said curing of said first outermost adhesive layer forms a substantially homogenous surface over said at least a portion of said surface of said bare semiconductor die suitable for laser marking.

7. (Currently amended) The ~~laser-markable~~ laser-markable tape of claim 3, wherein said second adhesive layer is cured by exposure to an electromagnetic radiation source.

8. (Currently amended) The ~~laser-markable~~ laser-markable tape of claim 1, wherein said tape comprises a flexible film material having translucent properties.

9. (Currently amended) A tape for use in the laser marking of a semiconductor device comprising:

a flexible film material; and

a ~~multi-layer~~ multilayer adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a ~~laser-markable~~ laser-markable surface upon exposure thereof to electromagnetic radiation; and  
a second adhesive layer disposed between said flexible film material and said first outermost adhesive layer.

10. (Original) The tape of claim 9, wherein said tape includes a tape for adhering to at least a portion of a surface of a bare semiconductor die.

11. (Previously presented) The tape of claim 10, wherein said tape includes a tape for adhering to said portion of said surface of said bare semiconductor die after backgrinding of said portion of said surface of said bare semiconductor die.

12. (Previously presented) The tape of claim 10, wherein said first outermost adhesive layer includes a first outermost adhesive layer for curing upon exposure to a source of electromagnetic radiation for attaching said first outermost adhesive layer to said at least a portion of said surface of said bare semiconductor die.

13. (Original) The tape of claim 12, wherein said curing of said first outermost adhesive layer provides a loss of adhesion between said first outermost adhesive layer and said second adhesive layer.

14. (Previously presented) The tape of claim 12, wherein said curing of said first outermost adhesive layer forms a substantially homogenous surface over said at least a portion of said surface of said bare semiconductor die suitable for providing a mark by laser marking.

15. (Previously presented) The tape of claim 11, wherein said second adhesive layer is cured by exposure to electromagnetic radiation.

16. (Previously presented) The tape of claim 9, wherein said flexible film material comprises a flexible film material having translucent properties.

17. (Previously presented) A tape for use in the marking of a semiconductor device comprising:

film material; and

at least two layers of adhesive including:

- a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a surface upon exposure thereof to electromagnetic radiation; and
- a second adhesive layer disposed between said film material and said first outermost adhesive layer.

18. (Original) The tape of claim 17, wherein said tape includes a tape for adhering to at least a portion of a surface of a bare semiconductor die.

19. (Previously presented) The tape of claim 18, wherein said tape includes a tape for adhering to said portion of said surface of said bare semiconductor die after a backgrinding process.

20. (Previously presented) The tape of claim 18, wherein said first outermost adhesive layer includes a first outermost adhesive layer for curing upon exposure to electromagnetic radiation for attaching said first outermost adhesive layer to said at least a portion of said surface of said bare semiconductor die.

21. (Original) The tape of claim 20, wherein said curing of said first outermost adhesive layer provides a loss of adhesion between said first outermost adhesive layer and said second adhesive layer.

22. (Previously presented) The tape of claim 20, wherein said curing of said first outermost adhesive layer forms a substantially homogenous surface over said at least said portion of said surface of a bare semiconductor die suitable for laser marking for forming a mark on said surface of said bare semiconductor die.

23. (Previously presented) The tape of claim 19, wherein said second adhesive layer includes a layer cured by exposure to electromagnetic radiation.

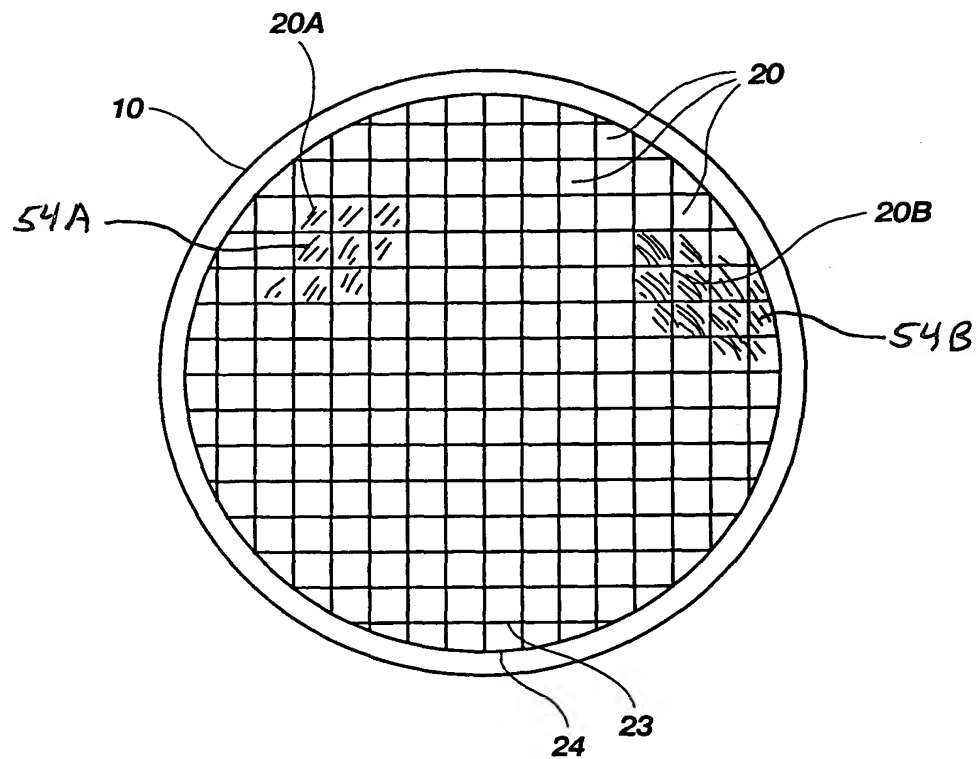
24. (Previously presented) The tape of claim 17, wherein said film material comprises a film material having translucent properties.

IN THE DRAWINGS:

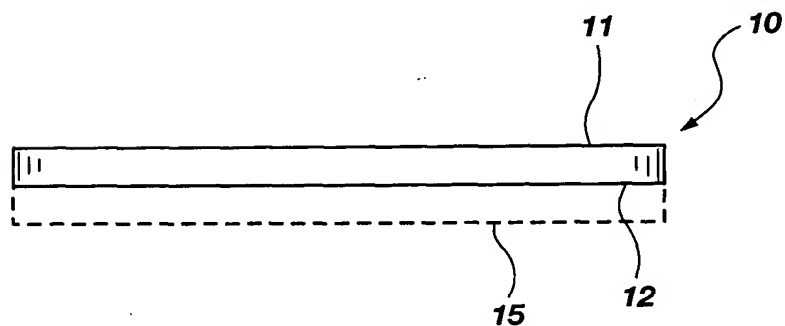
The attached sheet of drawings includes changes to FIGS. 1A. This sheet, which includes FIG. 1A, replaces the original sheet including FIGS. 1A and 1B.

Specifically, FIG. 1A has been revised to add the reference numerals --54A-- and --54B-- with their appropriate lead line. No new matter has been added.

**ANNOTATED SHEET  
SHOWING CHANGES**



**Fig. 1A**



**Fig. 1B**



AMENDMENTS TO THE ABSTRACT:

Please replace the Abstract originally appearing on page 21 of the application with the following rewritten paragraph:

ABSTRACT OF THE DISCLOSURE

The present invention provides a method and apparatus for marking a semiconductor wafer or device. The method and apparatus have particular application to wafers or devices which have been subjected to a thinning process, including backgrinding in particular. The present method comprises reducing the cross-section of a wafer or device, applying a tape having optical energy-markable properties over a surface or edge of the wafer or device, and exposing the tape to an optical energy source to create an identifiable mark. A method for manufacturing an integrated circuit chip and for identifying a known good die are also disclosed. The apparatus of the present invention comprises a ~~multi-level~~ multilevel laser-markable tape for application to a bare semiconductor die. In the apparatus, an adhesive layer of the tape provides a homogenous surface for marking subsequent to exposure to ~~electro-magnetic~~ electromagnetic radiation.